



Material Content Data Sheet



Sales Product Name				BTS442E2 E3062A		Issued		20. July 2018	
MA#				MA000689110					
Package				PG-TO263-5-2		Weight*		1504.45 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	20.863	1.39	1.39	13867	13867	
leadframe	non noble metal	iron	7439-89-6	0.790	0.05		525		
	inorganic material	phosphorus	7723-14-0	0.237	0.02		157		
	non noble metal	copper	7440-50-8	788.527	52.39	52.46	524130	524812	
	non noble metal	aluminium	7429-90-5	15.974	1.06	1.06	10618	10618	
wire	non noble metal	aluminium	7429-90-5	15.974	1.06	1.06	10618	10618	
encapsulation	organic material	carbon black	1333-86-4	6.034	0.40		4011		
	inorganic material	antimonytrioxide	1309-64-4	12.617	0.84		8387		
	plastics	brominated resin	-	14.263	0.95		9481		
	plastics	epoxy resin	-	104.231	6.93		69282		
	inorganic material	silicondioxide	60676-86-0	411.438	27.35	36.47	273482	364643	
leadfinish	non noble metal	tin	7440-31-5	10.469	0.70	0.70	6959	6959	
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5		
	non noble metal	nickel	7440-02-0	3.422	0.23	0.23	2274	2279	
glue	plastics	Polyimide	26023-21-2	0.733	0.05	0.05	487	487	
solder	noble metal	silver	7440-22-4	0.169	0.01		112		
	non noble metal	tin	7440-31-5	0.135	0.01		90		
	non noble metal	lead	7439-92-1	6.453	0.43	0.45	4289	4491	
heatspreader	non noble metal	iron	7439-89-6	0.108	0.01		72		
	inorganic material	phosphorus	7723-14-0	0.032	0.00		22		
	non noble metal	copper	7440-50-8	107.943	7.18	7.19	71750	71844	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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